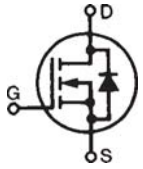
IXYS

Power MOSFET

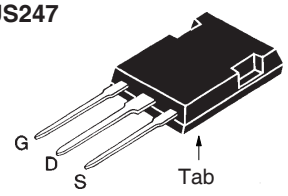
IXTX24N100

V_{DSS} = 1000V
I_{D25} = 24A
$R_{DS(on)}$ ≤ 400mΩ

N-Channel Enhancement Mode
Avalanche Rated



PLUS247



G = Gate D = Drain
S = Source Tab = Drain

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 150°C	1000	V
V_{DGR}	T_J = 25°C to 150°C, R_{GS} = 1MΩ	1000	V
V_{GSS}	Continuous	±20	V
V_{GSM}	Transient	±30	V
I_{D25}	T_C = 25°C	24	A
I_{DM}	T_C = 25°C	96	A
I_A	T_C = 25°C	24	A
E_{AS}	T_C = 25°C	3	J
dV/dt	$I_S \le I_{DM}$, $V_{DD} \le V_{DSS}$, $T_J \le 150°C$	5	V/ns
P_D	T_C = 25°C	568	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
T_L	1.6mm (0.062 in.) from Case for 10s	300	°C
T_{SOLD}	Plastic body for 10s	260	°C
M_d	Mounting Force	20..120 / 4.5..27	N/lb.
Weight		6	g

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
BV_{DSS}	V_{GS} = 0V, I_D = 3mA	1000			V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, I_D = 8mA	3.0		5.5	V
I_{GSS}	V_{GS} = ±20V, V_{DS} = 0V			±100	nA
I_{DSS}	$V_{DS} = V_{DSS}$, V_{GS} = 0V			50	μA
	T_J = 125°C			1	mA
$R_{DS(on)}$	V_{GS} = 10V, $I_D = 0.5 \bullet I_{D25}$, Note 1			400	mΩ

Features

- International Standard Package
- Low $R_{DS(on)}$ HDMOS™ Process
- Rugged Polysilicon Gate Cell Structure
- Avalanche Rated
- Low Package Inductance

Advantages

- PLUS 247™ Package for Clip or Spring Mounting
- Space Savings
- High Power Density

Applications

- DC-DC Converters
- Battery Chargers
- Switch-Mode and Resonant-Mode Power Supplies
- DC Choppers
- AC Motor Drives
- Temperature and Lighting Controls

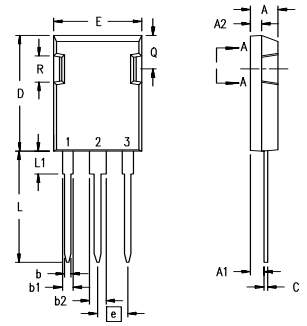
Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	V_{DS} = 10V, I_D = 0.5 • I_{D25}, Note 1	15	27		S
C_{iss}	V_{GS} = 0V, V_{DS} = 25V, f = 1MHz		8700		pF
C_{oss}			785		pF
C_{rss}			315		pF
$t_{d(on)}$	**Resistive Switching Times**		35		ns
t_r	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		35		ns
$t_{d(off)}$	R_G = 1Ω (External)		75		ns
t_f			21		ns
$Q_{g(on)}$	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		267		nC
Q_{gs}			52		nC
Q_{gd}			142		nC
R_{thJC}				0.22	°C/W
R_{thCS}			0.15		°C/W

Source-Drain Diode

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
I_S	V_{GS} = 0V			24	A
I_{SM}	Repetitive, Pulse Width Limited by T_{JM}			96	A
V_{SD}	I_F = 24A, V_{GS} = 0V, Note 1			1.5	V
t_{rr}	I_F = 24A, -di/dt = 100A/μs, V_R = 100V, V_{GS} = 0V		850		ns

Note 1: Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.

PLUS 247™ (IXTX) Outline



Terminals: 1 - Gate
2 - Drain
3 - Source

Dim.	Millimeter Min.	Max.	Inches Min.	Max.
A	4.83	5.21	.190	.205
A_1	2.29	2.54	.090	.100
A_2	1.91	2.16	.075	.085
b	1.14	1.40	.045	.055
b_1	1.91	2.13	.075	.084
b_2	2.92	3.12	.115	.123
C	0.61	0.80	.024	.031
D	20.80	21.34	.819	.840
E	15.75	16.13	.620	.635
e	5.45 BSC		.215 BSC	
L	19.81	20.32	.780	.800
L1	3.81	4.32	.150	.170
Q	5.59	6.20	.220	0.244
R	4.32	4.83	.170	.190

Fig. 1. Output Characteristics @ T_J = 25ºC

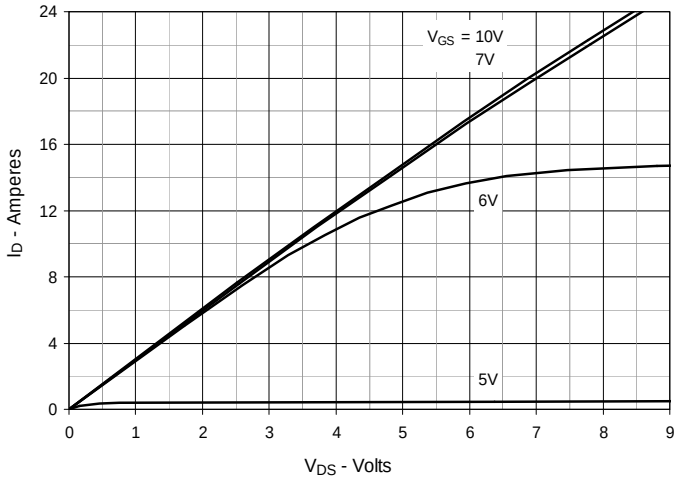


Fig. 2. Extended Output Characteristics @ T_J = 25ºC

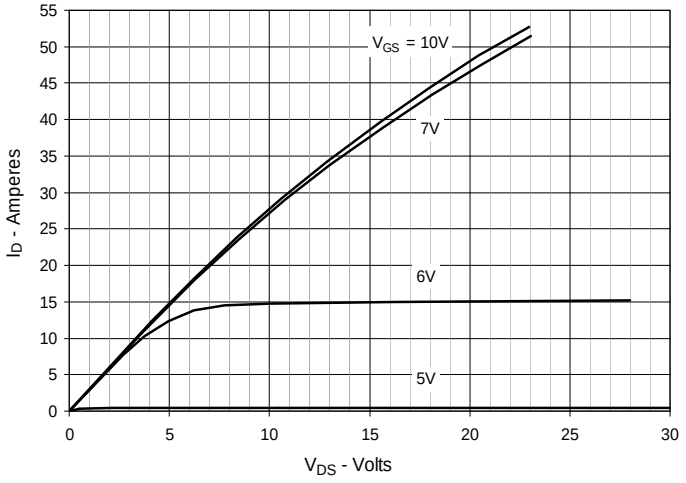


Fig. 3. Output Characteristics @ T_J = 125ºC

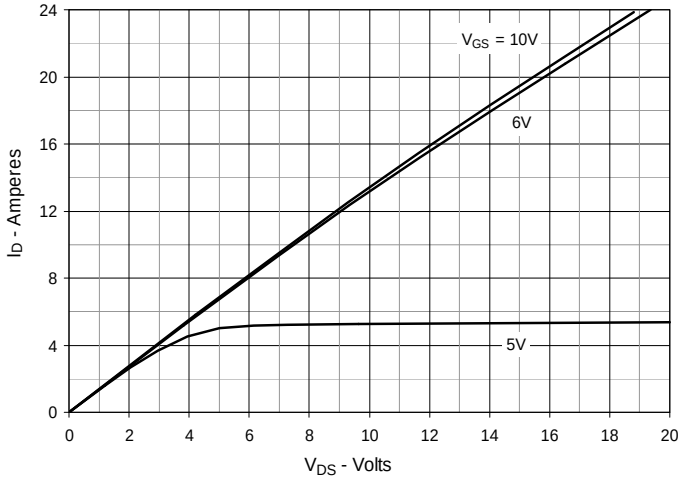


Fig. 4. $R_{DS(on)}$ Normalized to I_D = 12A Value vs. Junction Temperature

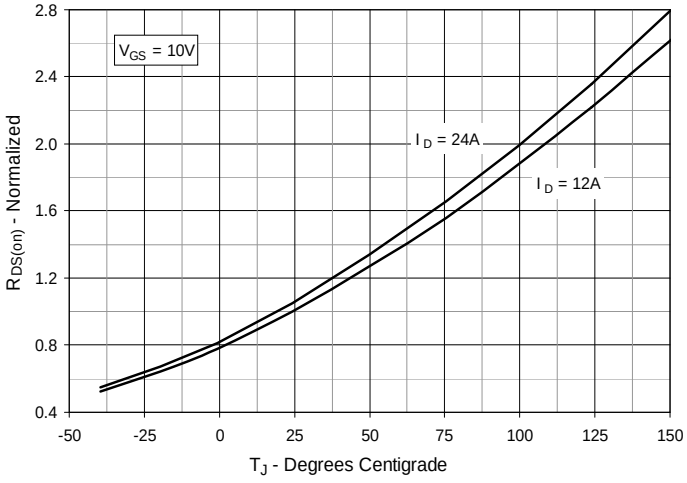


Fig. 5. $R_{DS(on)}$ Normalized to I_D = 12A Value vs. Drain Current

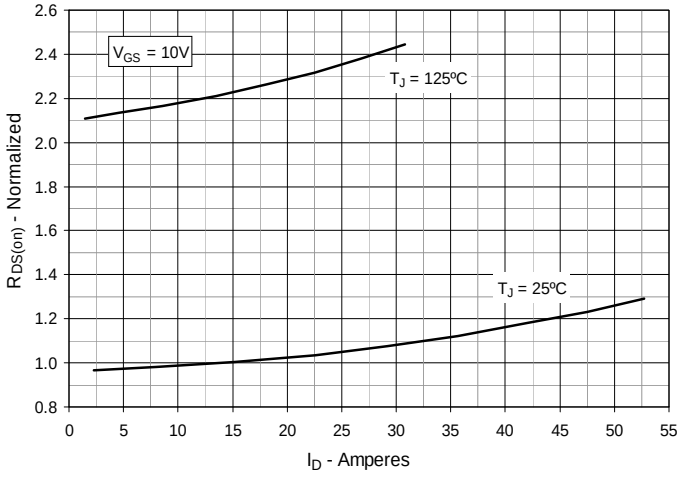


Fig. 6. Maximum Drain Current vs. Case Temperature

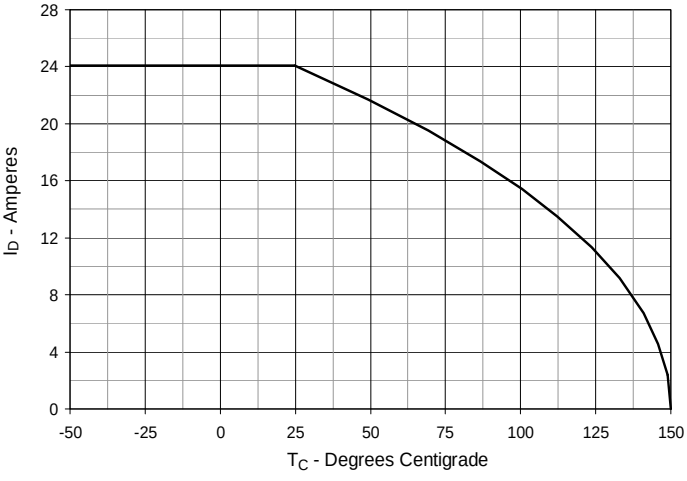


Fig. 7. Input Admittance

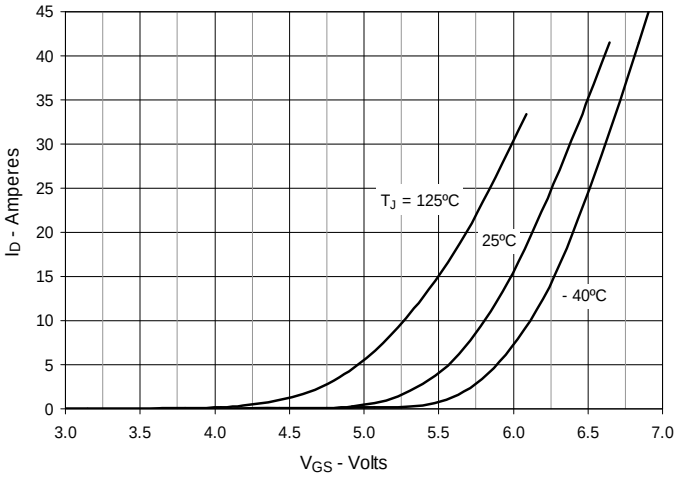


Fig. 8. Transconductance

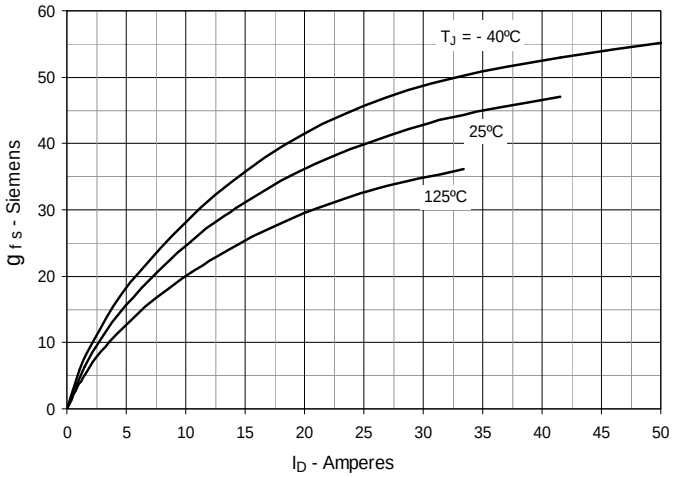


Fig. 9. Forward Voltage Drop of Intrinsic Diode

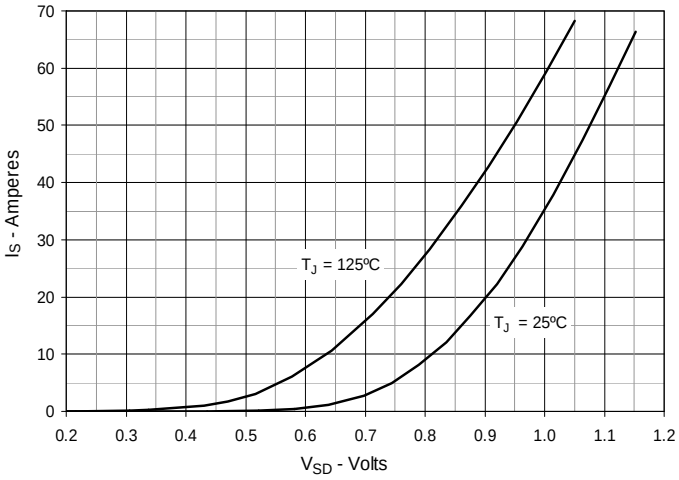


Fig. 10. Gate Charge

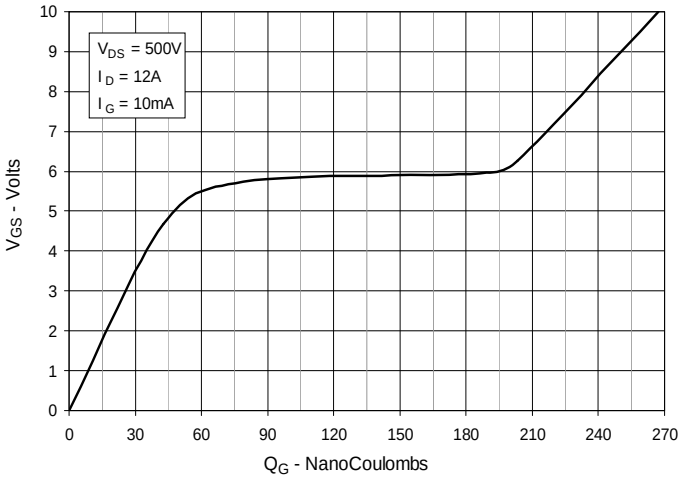


Fig. 11. Capacitance

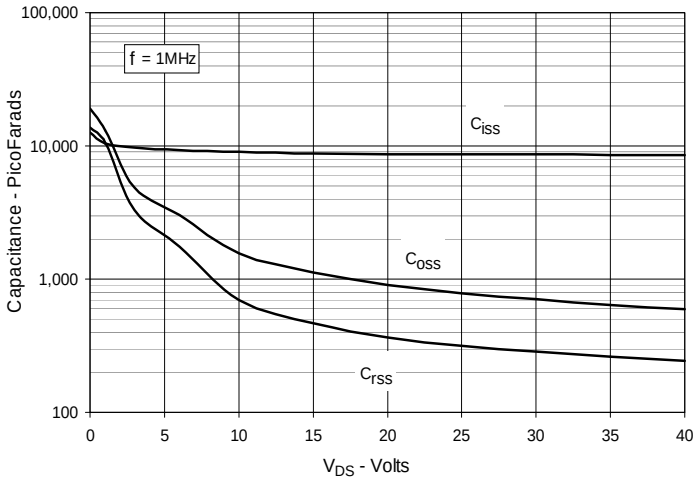


Fig. 12. Maximum Transient Thermal Impedance